



德砚电子

DE YAN DIAN ZI

# 一体成型功率电感

## *Data Sheet*

**RoHS**



**ISO 9001**  
质量管理体系认证



**ISO 14001**  
环境管理体系认证

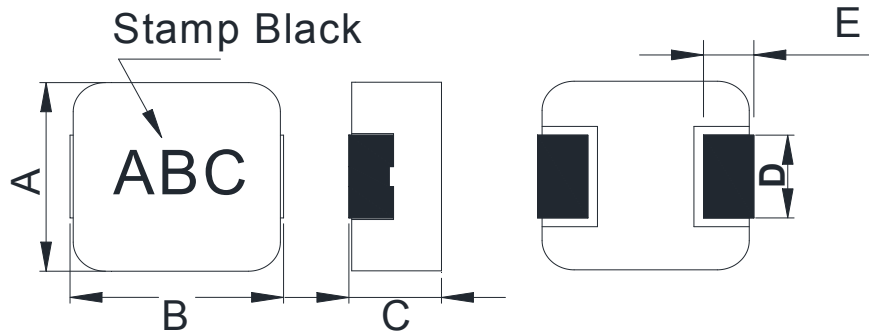
Shenzhen Deyan Electronics Co., Ltd



# \*SPECIFICATION\*

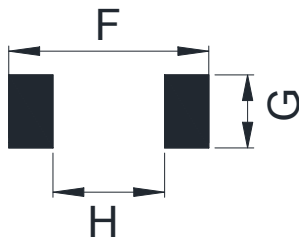
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		D0530HP-6R8MT		2024-07-03	--	01	1/5

## 1. DIMENSIONS (UNIT : mm)



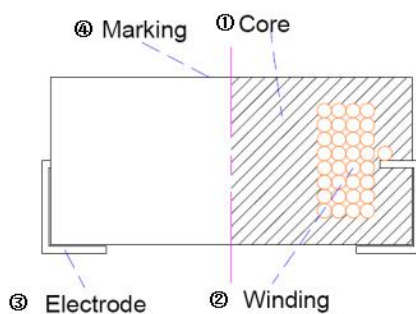
A	B	C	D	E
5.4±0.35	5.7±0.20	3.0 Max.	2.0±0.30	1.5±0.30

## 2. RECOMMENDED LAND PATTERN (UNIT: mm)



F	6.0 Ref.
G	2.5 Ref.
H	2.2 Ref.

## 3. STRUCTURE



No.	PARTS	MATERIAL
①	CORE	Alloy powder
②	WIRE	Self bonding polyamide-imide enameled Copper Wire
③	ELECTRODE	Cu
④	MARKING	INK

APPROVAL	CHECK	DESIGN	

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## 4.CHARACTERISTICS

No.	P/N.	Inductance ( $\mu\text{H}$ )	Stamp	D.C.R. (m $\Omega$ ) Max.	Saturation current(A)		Temperature rise current(A) ( $\Delta T \leq 40^\circ\text{C}$ )	
					Typ.	MAX	Typ.	MAX
01	D0530HP-6R8MT	6.8 $\pm$ 20%	6R8	110	5.0	4.0	3.0	2.5

\* Testing instrument: Inductance HP 4284A or equivalent at 100KHz /1V..

D.C.R : TH2512B or equivalent. ( $T_a = 25^\circ\text{C}$ )

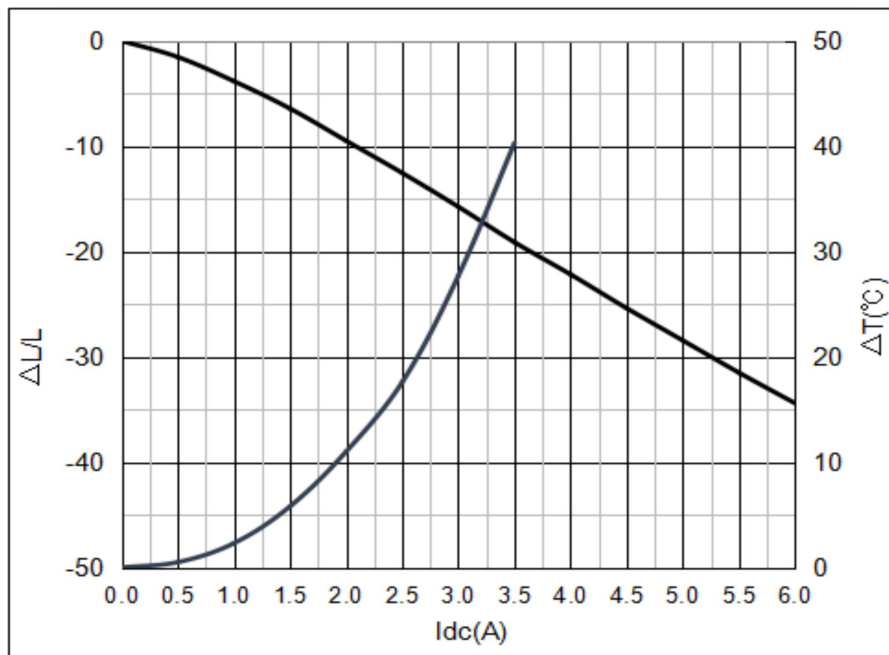
Saturation current: WK 3260B+3265B or equivalent.

\* Saturation Current ( $I_{\text{sat}}$ ) will cause  $L_0$  to drop approximately 30% from its value without current. ( $T_a = 25^\circ\text{C}$ )

\* The temperature rise current value is the DC current value having temperature increase up to approximately  $40^\circ\text{C}$  ( $T_a = 25^\circ\text{C}$ )

\* Absolute maximum voltage 30VDC

6R8 DC Bias & Temperature Characteristics



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## 5. GENERAL CHARACTERISTICS

\* STANDARD TESTING CONDITIONS:

UNLESS OTHERWISE SPECIFIED, THE STANDARD RANGE OF ATMOSPHERIC CONDITIONS FOR MEASUREMENTS AND TESTS ARE AS FOLLOWS: AMBIENT TEMPERATURE: 15°C~35°C.

RELATIVE HUMIDITY : 25% ~85%. AIR PRESSURE : 86kPa ~106kPa.

IF THERE IS ANY DOUBT ABOUT THE RESULTS, MEASUREMENT SHALL BE MADE WITHIN THE FOLLOWING LIMITS: AMBIENT TEMPERATURE: 20°C±1°C. RELATIVE HUMIDITY: 63% ~67%.

AIR PRESSURE : 86kPa ~106kPa.

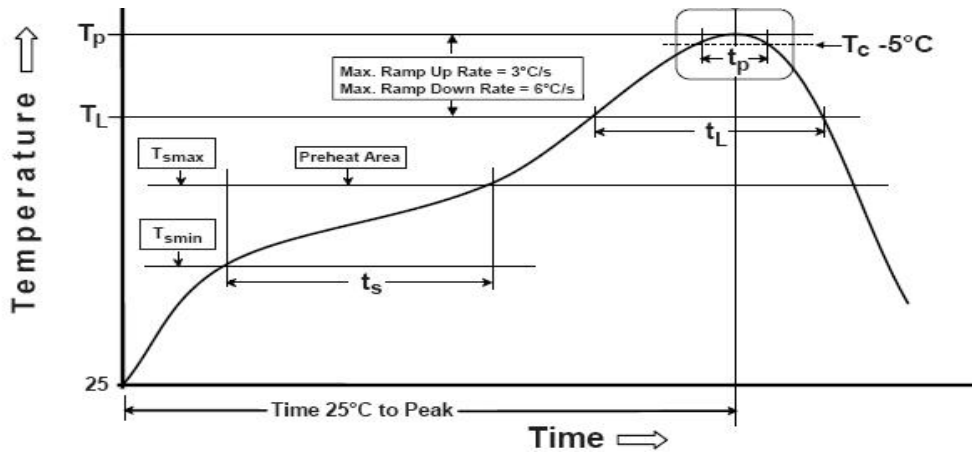
No.	ITEMS	CONDITIONS	SPECIFICATION
1	OPERATION TEMPERATURE  STORAGE TEMPERATURE		-40 ~ + 125°C (INCLUDING COIL TEMPERATURE RISE) -40 ~ + 125°C
2	TEMPERATURE COEFFICIENT	-30 ~ +105°C	0 ~ 2000 ppm/°C
3	FIXING STRENGTH	SAMPLE IS PUSHED IN THREE DIRECTIONS OF X, Y AND Z WITH FORCE OF 5. 0N FOR 10±5 SECONDS. AFTER SOLDERING BETWEEN COPPER PLATE AND ELECTRODES.	NO ELECTRODE DETACHMENT.
4	RESISTANCE TO SOLDERING HEAT TEST	REFER TO THE SPEC "STD-001NP".	NO MECHANICAL BREAKAGE. DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
5	SOLDERABILITY TEST	IMMERSE THE ELECTRODE IN FLUX FOR 5 SECONDS. THEN DIP THE ELECTRODE INTO A SOLDERING BATH OF 245±5°C FOR 2±0.5 SECONDS.	OVER 95% OF THE SURFACE BEING IMMersed SHALL BE COVERED WITH NEW SOLDER UNIFORMLY.
6	VIBRATION TEST	AMPLITUDE: 1.5mm P-P FREQUENCY:10~55~10Hz (1 MINUTE PER CYCLE) DURATION: 1 HOUR IN EACH OF X, Y, Z AXIS.	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
7	HUMIDITY TEST	TEMPERATURE: 40°C±2°C HUMIDITY: 90%~95%RH DURATION: 96±4 HOURS.	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
8	THERMAL SHOCK TEST	20 CYCLES OF +105°C FOR 30 MINUTES, -40 °C FOR 30 MINUTES. CHARACTERISTICS ARE MEASURED AFTER THE AMBIENT AIR EXPOSURE OF 1 HOUR	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
9	HIGH TEMPERATURE STORAGE TEST	TEMPERATURE: 125°C±2°C DURATION: 96±4 HOURS	
10	LOW TEMPERATURE STORAGE TEST	TEMPERATURE: -40°C±3°C DURATION: 96±4 HOURS.	

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## 6. Reflow profile for SMT components



Reflow is referred to standard IPC/ JEDEC J-STD-020D

Profile Feature		Lead(Pb) Free solder
Preheat and soak	·temperature Min.( $T_{smin}$ )	150°C
	·temperature Max.( $T_{smax}$ )	200°C
	·time( $T_{smin}$ to $T_{smax}$ )( $t_s$ )	60-120 Seconds
Average ramp up rate $T_{smax}$ to $T_p$		3°C/Second Max.
Liquidous temperature ( $T_L$ )		217 °C
Time ( $T_L$ ) maintained above $T_L$		60-150 seconds
Peak package body temperature ( $T_p$ )		<b>Table2</b>
Time ( $t_p$ )* within 5 °C of the specified classification temperature ( $T_c$ )		30* seconds
Average Ramp-down rate ( $T_p$ to $T_L$ )		6 °C/second max
Time 25 °C to peak temperature		8 minutes max.

**Table2. Pb-Free Process - Classification Temperatures ( $T_c$ )**

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350~2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260°C	260°C	260°C
1.6mm- 2.5mm	260°C	250°C	245°C
>2.5 mm	250°C	245°C	245°C

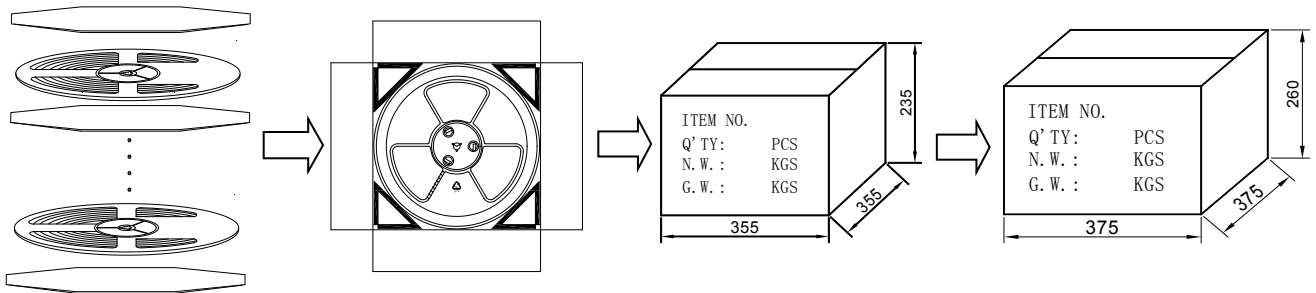
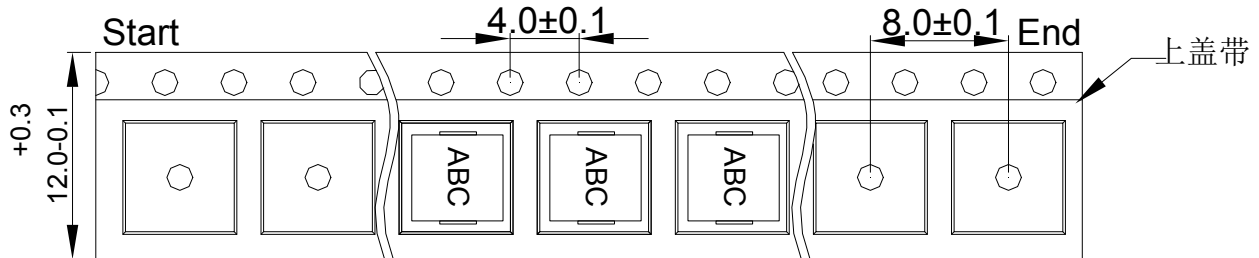
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## 7. PACKING

REFER TO STANDARD PACKING DRAWING. 2000PCS/R



REEL	2000PCS
BOX	20000PCS

## 8. NOTE

SOLDERING TIN PERIOD OF VALIDITY: SIX MONTHS  
 STORAGE TEMPERATURE: 25°C±5°C  
 COMPARATIVELY HUMIDITY: 35%--70%

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